LM79LXXAC Series 3-Terminal Negative Regulators

Check for Samples: LM79L05, LM79L05AC, LM79L12, LM79L12AC, LM79L15, LM79L15AC

FEATURES

- **Preset Output Voltage Error is Less than ±5% Overload, Line and Temperature**
- **Specified at an Output Current of 100mA**
- **Easily Compensated with a Small 0.1µF Output**
  - **Capacitor**
- **Internal Short-Circuit, Thermal and Safe Operating Area Protection**
- **Easily Adjustable to Higher Output Voltages**
- **Maximum Line Regulation Less than 0.07% V_{OUT}/V**
- **Maximum Load Regulation Less than 0.01% V_{OUT}/mA**
- **See AN-1112 (SNVA009) for DSBGA Considerations**

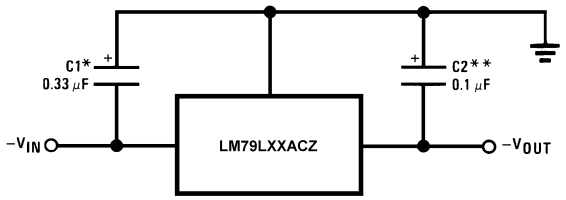
DESCRIPTION

The LM79LXXAC series of 3-terminal negative voltage regulators features fixed output voltages of −5V, −12V, and −15V with output current capabilities in excess of 100mA. These devices were designed using the latest computer techniques for optimizing the packaged IC thermal/electrical performance. The LM79LXXAC series, when combined with a minimum output capacitor of 0.1µF, exhibits an excellent transient response, a maximum line regulation of 0.07% V_O/V, and a maximum load regulation of 0.01% V_O/mA.

The LM79LXXAC series also includes, as self-protection circuitry: safe operating area circuitry for output transistor power dissipation limiting, a temperature independent short circuit current limit for peak output current limiting, and a thermal shutdown circuit to prevent excessive junction temperature. Although designed primarily as fixed voltage regulators, these devices may be combined with simple external circuitry for boosted and/or adjustable voltages and currents. The LM79LXXAC series is available in the 3-lead TO package, the 8-lead SOIC package, and the 6-Bump DSBGA package.

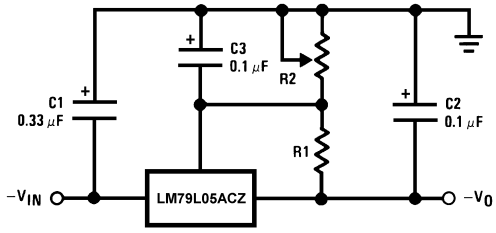
For output voltages other than the pre-set -5V, -12V and -15V, the LM137L series provides an adjustable output voltage range from -1.2V to -47V.

Typical Applications



*Required if the regulator is located far from the power supply filter. A 1µF aluminum electrolytic may be substituted.
**Required for stability. A 1µF aluminum electrolytic may be substituted.

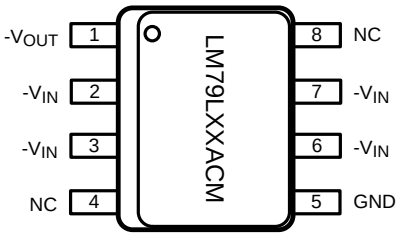
Figure 1. Fixed Output Regulator



$-V_0 = -5V - (5V/R1 + I_Q) \bullet R2$,
$5V/R1 > 3\ I_Q$

Figure 2. Adjustable Output Regulator

Connection Diagram



Pins labeled 'NC' on LM79LXXACM 8-Lead SOIC (pin 4 and pin 8) are Open, no internal connection.

Figure 3. 8-Lead SOIC Narrow (D)
Top View

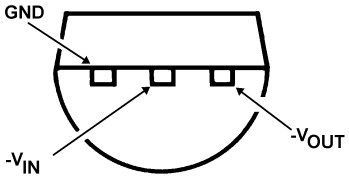


Figure 4. 3–Lead TO (LP)
Bottom View

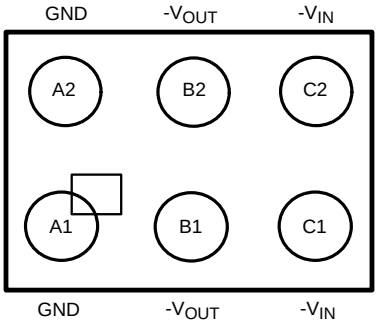


Figure 5. 6-Bump DSBGA
Top View (Bump Side Down)

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1) (2)

Input Voltage	
V_O = −5V, −12V, −15V	−35V
Internal Power Dissipation (3)	Internally Limited
Operating Temperature Range	0°C to +70°C
Maximum Junction Temperature	+125°C
Storage Temperature Range	−55°C to +150°C
Lead Temperature	
(Soldering, 10 sec.)	260°C

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) Thermal resistance of TO-3 (LP) package is 60°C/W θ_{JC}, 232°C/W θ_{JA} at still air, and 88°C/W at 400 ft/min of air. The θ_{JA} of the LM78LXX in the 6-Bump DSBGA package is 114°C/W when mounted on a 4-Layer JEDEC test board (JESD 51-7). The θ_{JA} of the LM78LXX in the SOIC-8 (D) package is 180°C/W in still air. The maximum junction temperature shall not exceed 125°C on electrical parameters.

Electrical Characteristics (1)

T_A = 0°C to +70°C unless otherwise noted.

Output Voltage			**−5V**			**−12V**			**−15V**			
Input Voltage (unless otherwise noted)			**−10V**			**−17V**			**−20V**			
Symbol	**Parameter**	**Conditions**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Units**
V_O	Output Voltage	T_J = 25°C, I_O = 100mA	−5.2	−5	−4.8	−12.5	−12	−11.5	−15.6	−15	−14.4	V
		1mA ≤ I_O ≤ 100mA	−5.25		−4.75	−12.6		−11.4	−15.75		−14.25	
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.5)			(−27 ≤ V_{IN} ≤ −14.8)			(−30 ≤ V_{IN} ≤ −18)			
		1mA ≤ I_O ≤ 40mA	−5.25		−4.75	−12.6		−11.4	−15.75		−14.25	
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7)			(−27 ≤ V_{IN} ≤ −14.5)			(−30 ≤ V_{IN} ≤ −17.5)			
ΔV_O	Line Regulation	T_J = 25°C, I_O = 100mA			60			45			45	mV
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.3)			(−27 ≤ V_{IN} ≤ −14.6)			(−30 ≤ V_{IN} ≤ −17.7)			V
		T_J = 25°C, I_O = 40mA			60			45			45	mV
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7)			(−27 ≤ V_{IN} ≤ −14.5)			(−30 ≤ V_{IN} ≤ −17.5)			V
ΔV_O	Load Regulation	T_J = 25°C			50			100			125	mV
		1mA ≤ I_O ≤ 100mA										
ΔV_O	Long Term Stability	I_O = 100mA		20			48			60		mV/khrs
I_Q	Quiescent Current	I_O = 100mA		2	6		2	6		2	6	mA
ΔI_Q	Quiescent Current Change	1mA ≤ I_O ≤ 100mA			0.3			0.3			0.3	
		1mA ≤ I_O ≤ 40mA			0.1			0.1			0.1	mA
		I_O = 100mA			0.25			0.25			0.25	mA
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.5)			(−27 ≤ V_{IN} ≤ −14.8)			(−30 ≤ V_{IN} ≤ −18)			V
V_n	Output Noise Voltage	T_J = 25°C, I_O = 100mA f = 10Hz − 10kHz		40			96			120		µV
$\Delta V_{IN}/\Delta V_O$	Ripple Rejection	T_J = 25°C, I_O = 100mA f = 120Hz	50			52			50			dB
	Input Voltage Required to Maintain Line Regulation	T_J = 25°C, I_O = 100mA			−7.3			−14.6			−17.7	V
		I_O = 40mA			−7.0			−14.5			−17.5	V

(1) To ensure constant junction temperature, low duty cycle pulse testing is used.

Typical Performance Characteristics

Maximum Average Power Dissipation (TO)

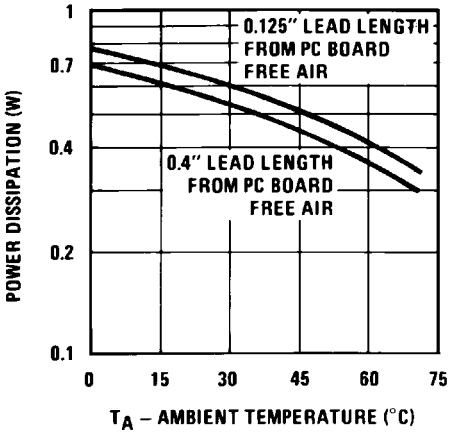


Figure 6.

Peak Output Current

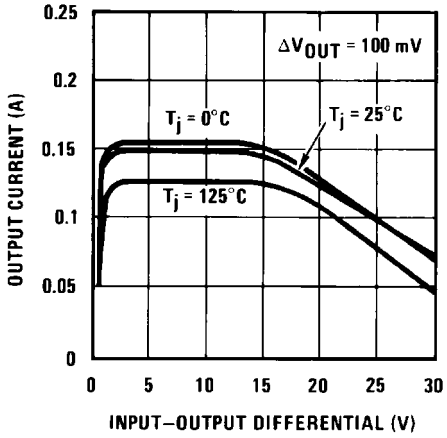


Figure 7.

Short Circuit Output Current

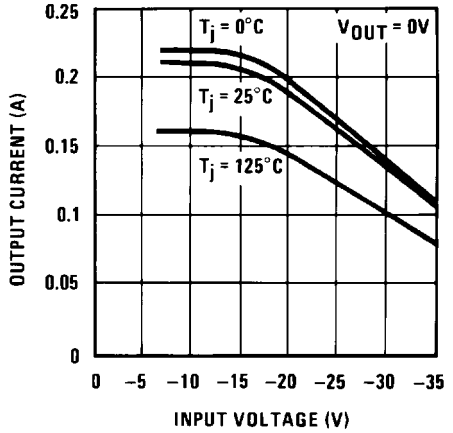


Figure 8.

Dropout Voltage

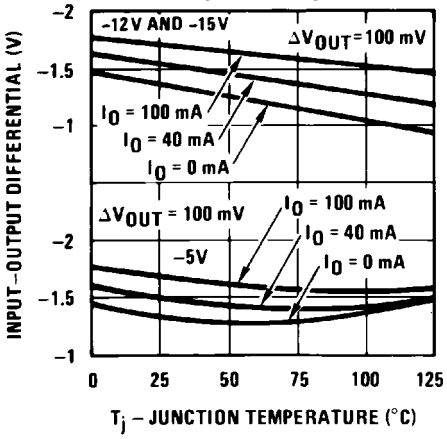


Figure 9.

Ripple Rejection

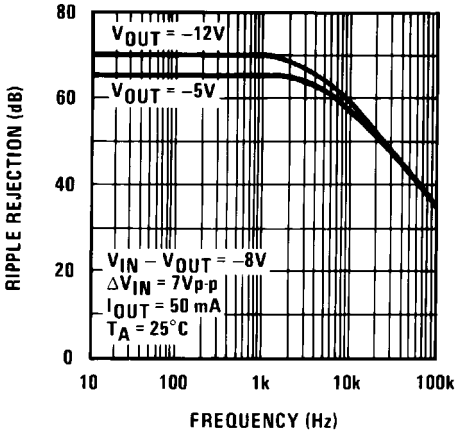


Figure 10.

Output Voltage vs. Temperature
(Normalized to 1V @ 25°C)

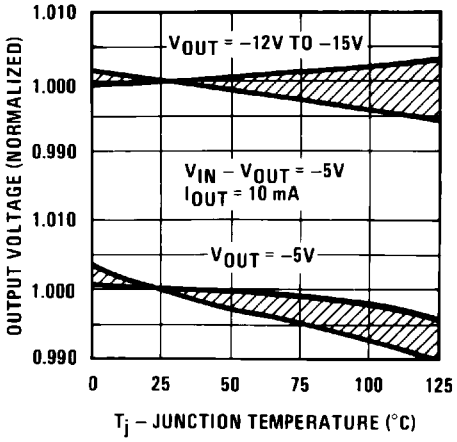


Figure 11.

Typical Performance Characteristics (continued)

Quiescent Current

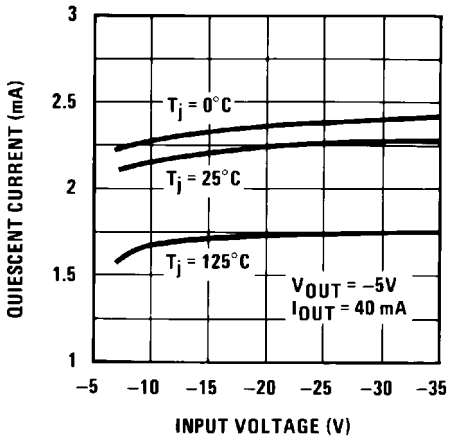


Figure 12.

Output Impedance

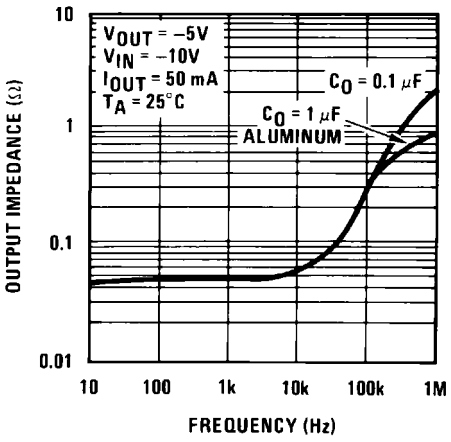


Figure 13.

TYPICAL APPLICATIONS

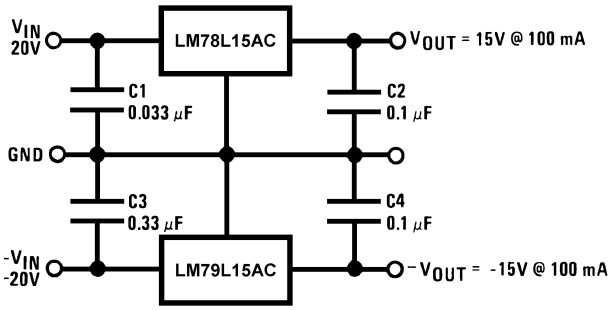


Figure 14. ±15V, 100mA Dual Power Supply

Schematic Diagrams

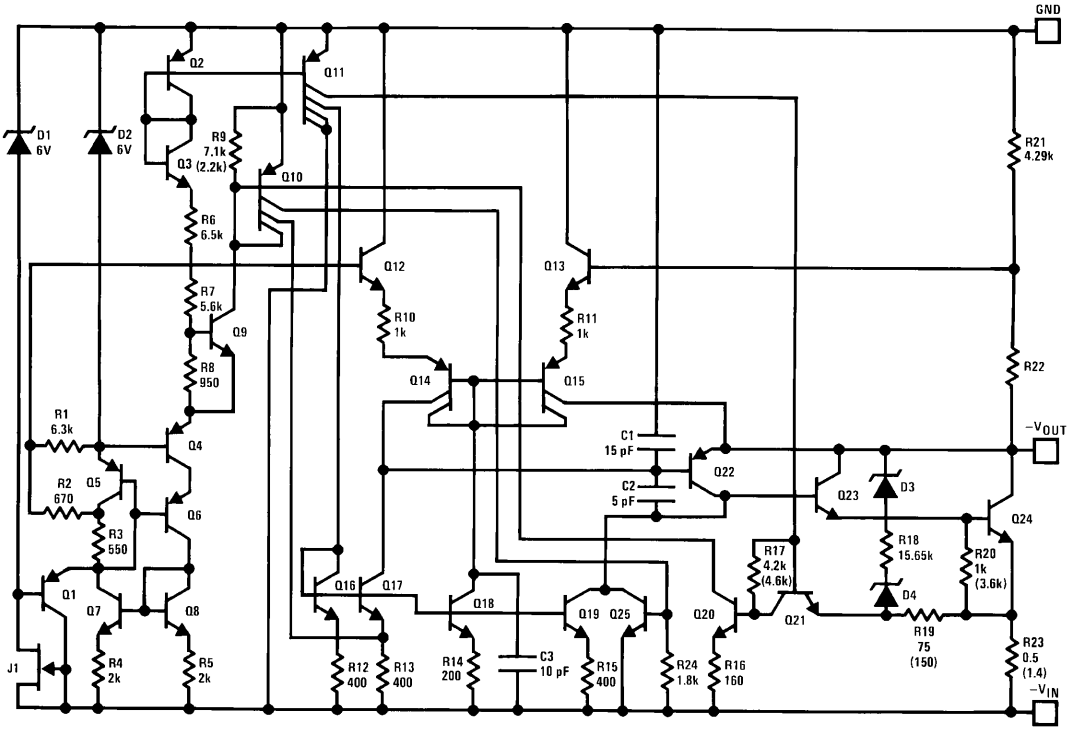


Figure 15. −5V Schematic Diagram

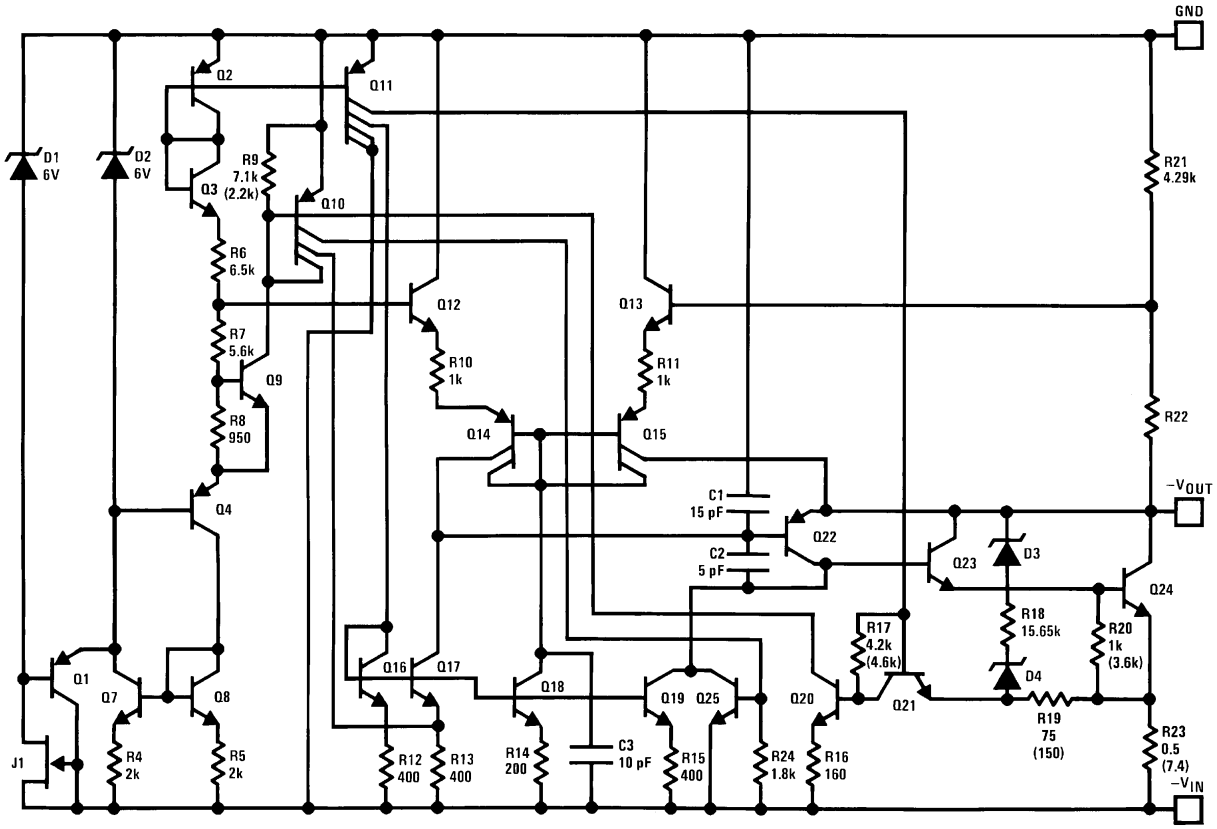


Figure 16. −12V and −15V Schematic Diagram

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
1.004.022	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 05ACM	Samples
LM79L05ACM	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 05ACM	Samples
LM79L05ACM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM	Samples
LM79L05ACMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 05ACM	Samples
LM79L05ACMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM	Samples
LM79L05ACTL/NOPB	ACTIVE	DSBGA	YZR	6	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B	Samples
LM79L05ACTLX/NOPB	ACTIVE	DSBGA	YZR	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B	Samples
LM79L05ACZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		320L 79L05	Samples
LM79L05ACZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	320L 79L05	Samples
LM79L12ACM	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 12ACM	Samples
LM79L12ACM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM	Samples
LM79L12ACMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 12ACM	Samples
LM79L12ACMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM	Samples
LM79L12ACZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		320L 79L12	Samples
LM79L12ACZ/LFT7	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		320L 79L12	Samples
LM79L12ACZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	320L 79L12	Samples
LM79L15ACM	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 15ACM	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM79L15ACM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM	Samples
LM79L15ACMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM79L 15ACM	Samples
LM79L15ACMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

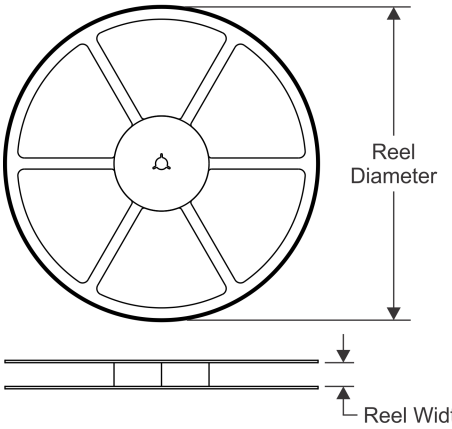
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

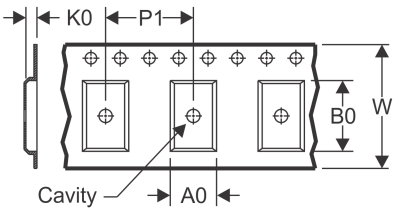
(4) Only one of markings shown within the brackets will appear on the physical device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

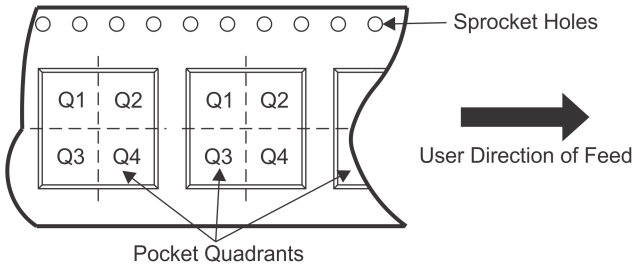


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

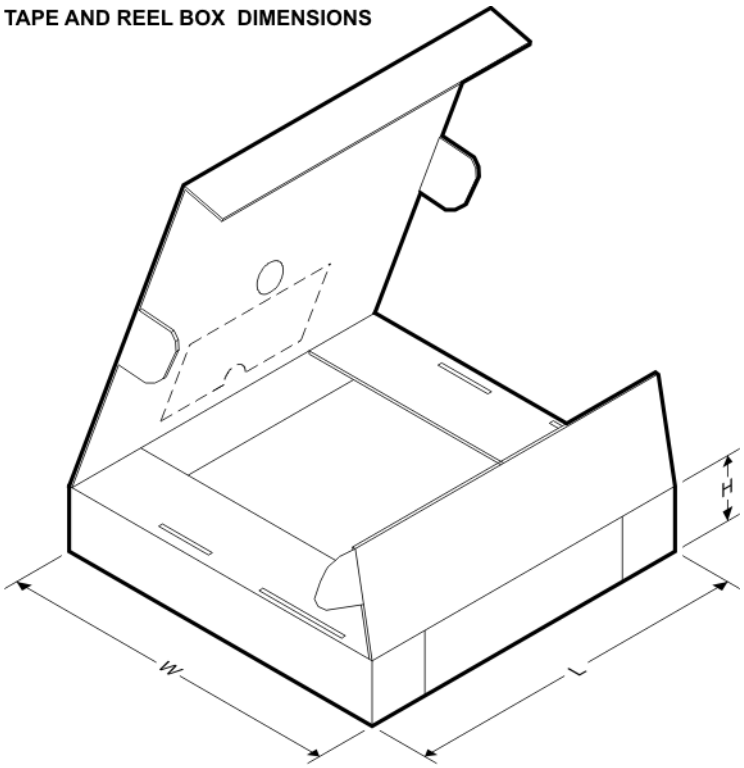
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM79L05ACMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L05ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L05ACTL/NOPB	DSBGA	YZR	6	250	178.0	8.4	1.09	1.88	0.76	4.0	8.0	Q1
LM79L05ACTLX/NOPB	DSBGA	YZR	6	3000	178.0	8.4	1.09	1.88	0.76	4.0	8.0	Q1
LM79L12ACMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L12ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L15ACMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L15ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

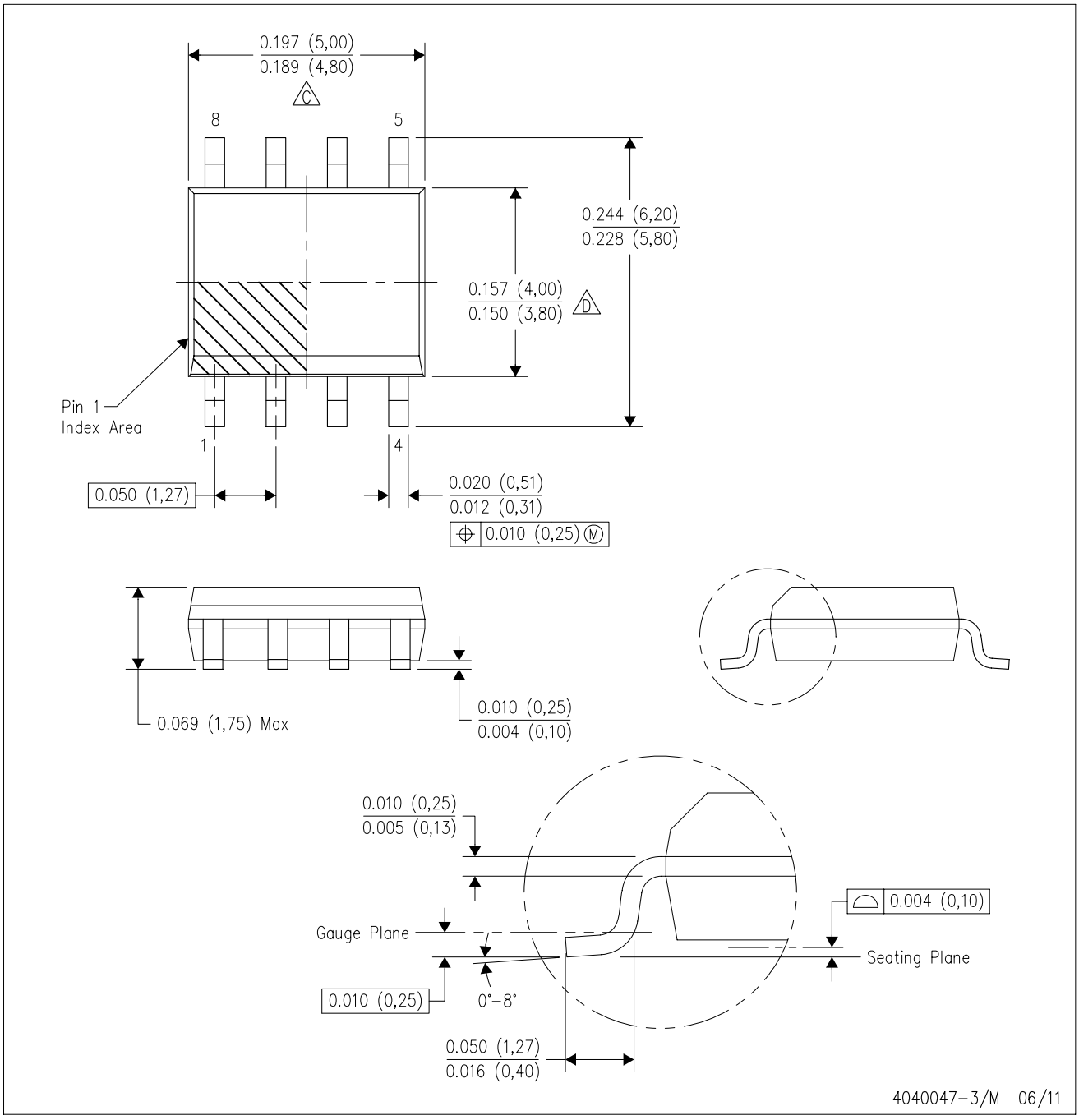
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

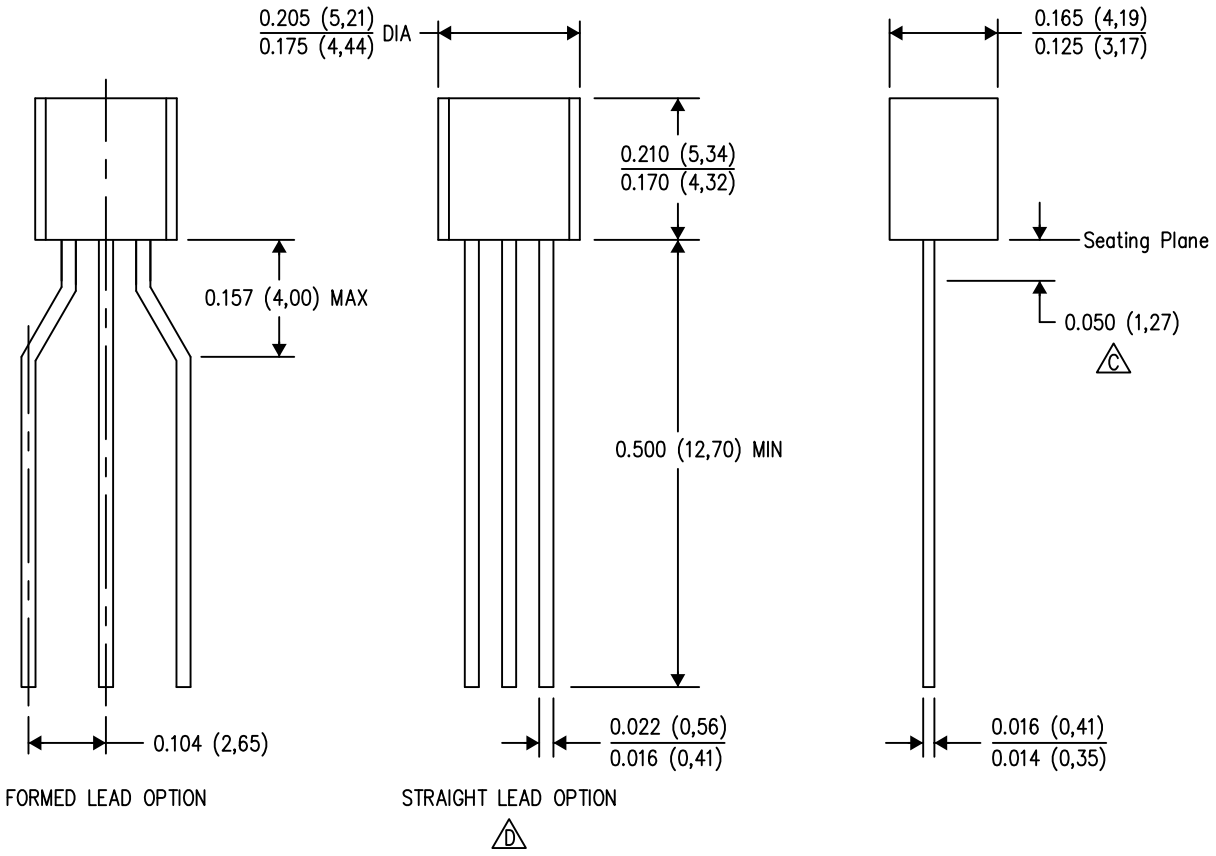
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM79L05ACMX	SOIC	D	8	2500	349.0	337.0	45.0
LM79L05ACMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0
LM79L05ACTL/NOPB	DSBGA	YZR	6	250	203.0	190.0	41.0
LM79L05ACTLX/NOPB	DSBGA	YZR	6	3000	206.0	191.0	90.0
LM79L12ACMX	SOIC	D	8	2500	349.0	337.0	45.0
LM79L12ACMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0
LM79L15ACMX	SOIC	D	8	2500	349.0	337.0	45.0
LM79L15ACMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0

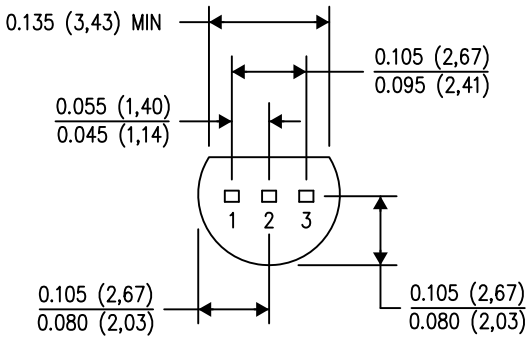
D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

LP (O–PBCY–W3) PLASTIC CYLINDRICAL PACKAGE

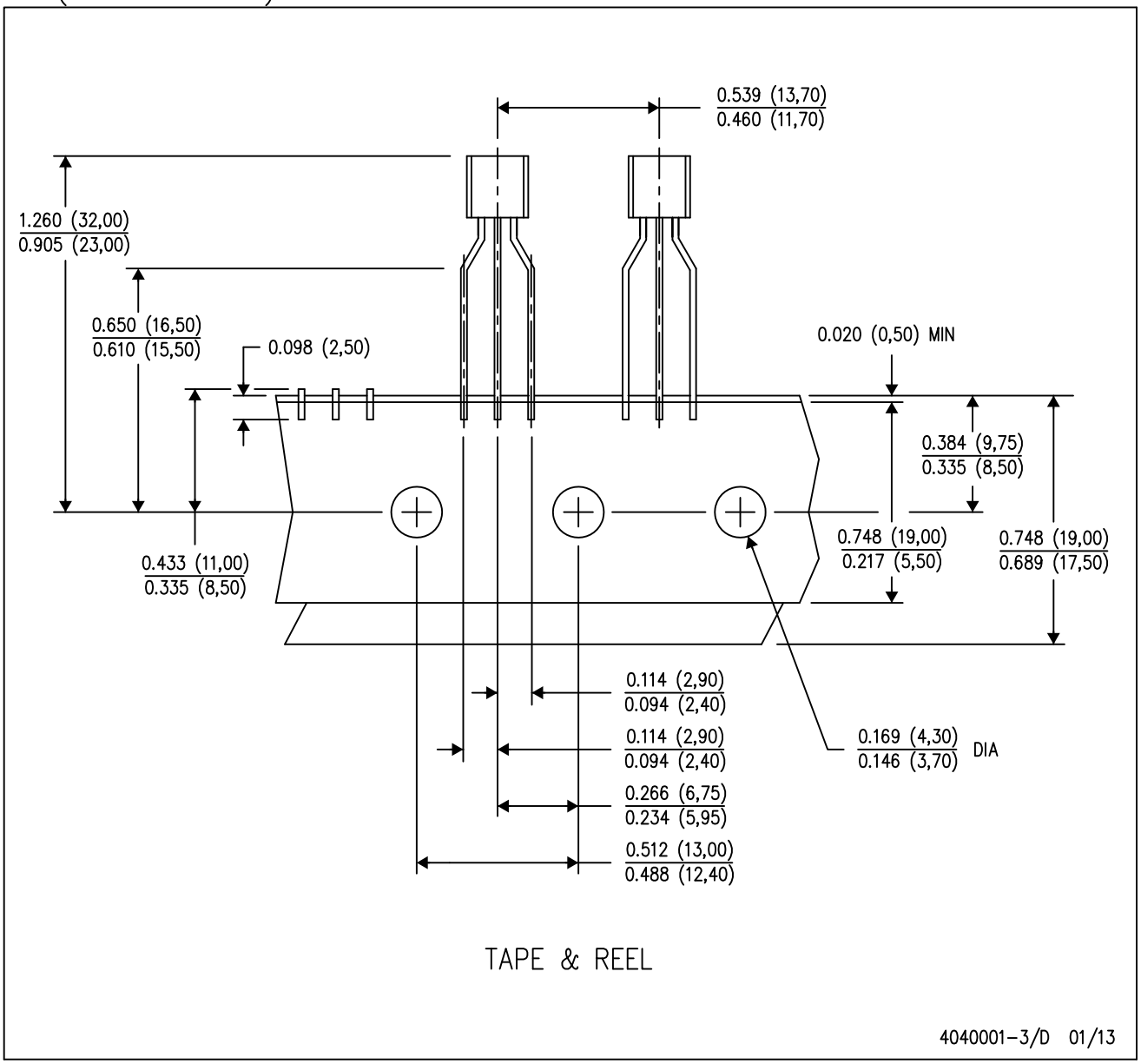




4040001–2/D 01/13

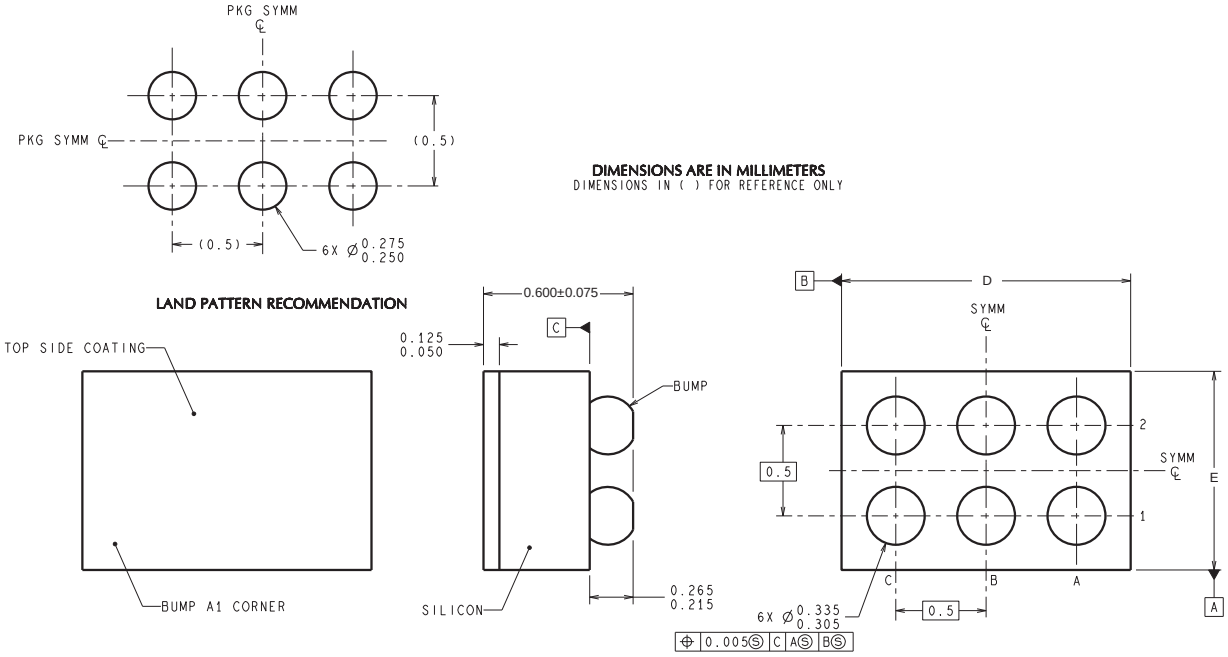
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Lead dimensions are not controlled within this area.
D. Falls within JEDEC TO–226 Variation AA (TO–226 replaces TO–92).
E. Shipping Method:
Straight lead option available in either bulk pack or tape & reel.
Formed lead option available in tape & reel or ammo pack.
Specific products can be offered in limited combinations of shipping mediums and lead options.
Consult product folder for more information on available options.

LP (O–PBCY–W3) PLASTIC CYLINDRICAL PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Tape and Reel information for the Formed Lead Option package.

YZR0006



TLA06XXX (Rev C)

D: Max = 1.865 mm, Min =1.764 mm

E: Max = 1.077 mm, Min =0.976 mm

4215044/A 12/12

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265